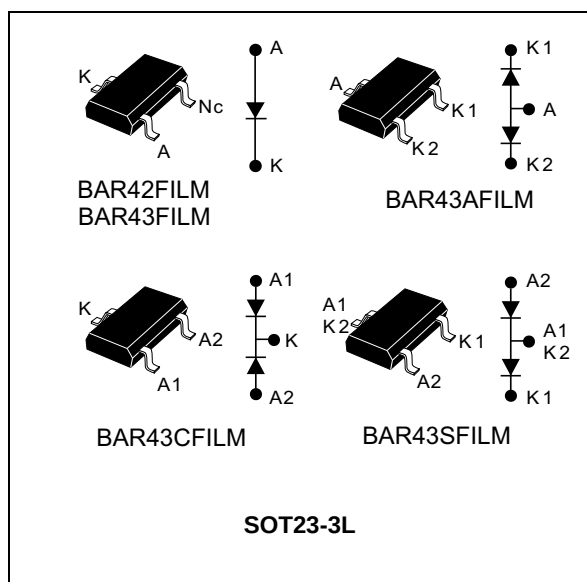




Description

General purpose metal to silicon diodes featuring very low turn-on voltage and fast switching.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	0.1 A
V_{RRM}	30 V
T_j	150 °C
V_F (max)	0.33 and 0.40 V

Features

- Very small conduction losses
- Negligible switching losses
- Low forward voltage drop
- Surface mount device

1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter		Value	Unit
V_{DRM}	Repetitive peak off-state voltage		30	V
$I_{F(AV)}$	Continuous forward current		0.1	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10$ ms sinusoidal	0.75	A
P_{tot}	Power dissipation ⁽¹⁾	$T_{amb} = 25$ °C	250	mW
T_{stg}	Maximum Storage temperature range		- 65 to + 150	°C
T_j	Maximum operating junction temperature ⁽²⁾		150	°C
T_L	Maximum temperature for soldering during 10 s		260	°C

1. For double diodes, P_{tot} is the total dissipation of both diodes
2. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 3. Thermal parameter

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient ⁽¹⁾	500	°C/W

1. Mounted on epoxy board with recommended pad layout.

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
V_{BR}	Breakdown voltage	$T_j = 25$ °C	$I_R = 100$ μ A	30			V
I_R ⁽¹⁾	Reverse leakage current	$T_j = 25$ °C	$V_R = V_{RRM}$			500	nA
		$T_j = 100$ °C				100	μ A
V_F ⁽²⁾	Forward voltage drop	$T_j = 25$ °C	BAR42	$I_F = 10$ mA		0.35	V
				$I_F = 50$ mA		0.50	
			BAR43	$I_F = 2$ mA	0.26	0.33	
				$I_F = 15$ mA		0.45	
			ALL	$I_F = 100$ mA		1	

1. Pulse test: $t_p = 5$ ms, $\delta < 2$ %
2. Pulse test: $t_p = 380$ μ s, $\delta < 2$ %

Table 5. Dynamic characteristics (T_j = 25 °C)

Symbol	Test conditions		Min.	Typ.	Max.	Unit
C	Junction capacitance	T _j = 25 °C V _R = 1 V F = 1 MHz		7		pF
C	Reverse recovery time	I _F = 10 mA I _R = 10 mA T _j = 25 °C I _{rr} = 1 mA R _L = 100 Ω			5	pF
η	Detection efficiency	C _L = 300 pF F = 45 MHz T _j = 25 °C V _i = 2 V R _L = 50 Ω	80			ps

Figure 1. Forward voltage drop versus forward current (typical values, low level)

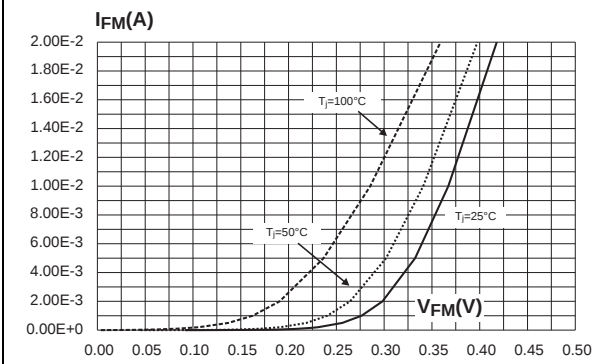


Figure 2. Forward voltage drop versus forward current (typical values, high level)

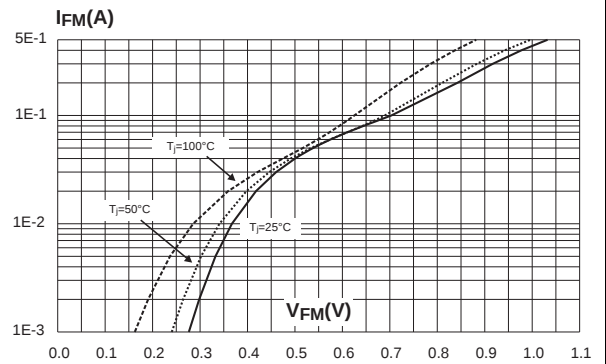


Figure 3. Reverse leakage current versus reverse voltage applied (typical values)

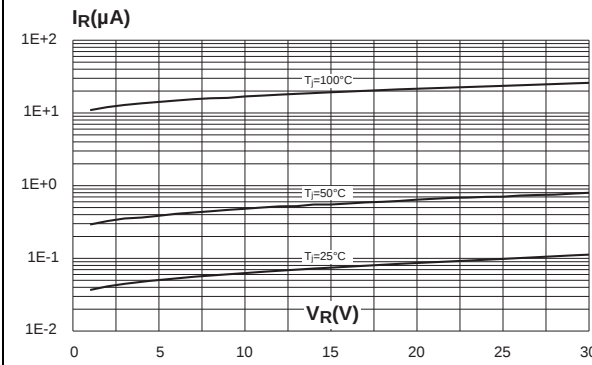


Figure 4. Reverse leakage current versus junction temperature

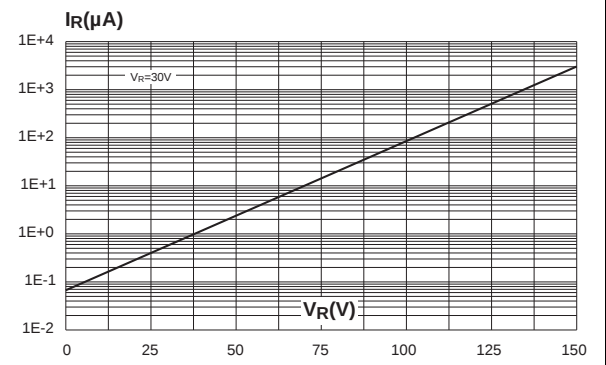


Figure 5. Junction capacitance versus reverse voltage applied (typical values)

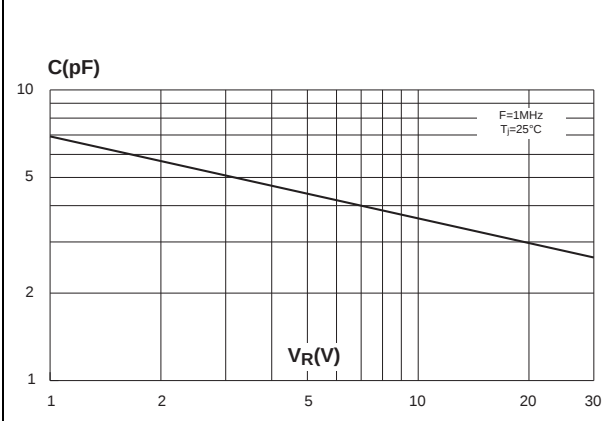


Figure 6. Relative variation of thermal impedance junction to ambient versus pulse duration

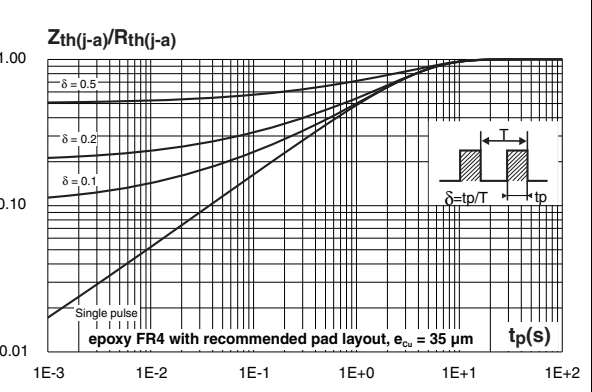
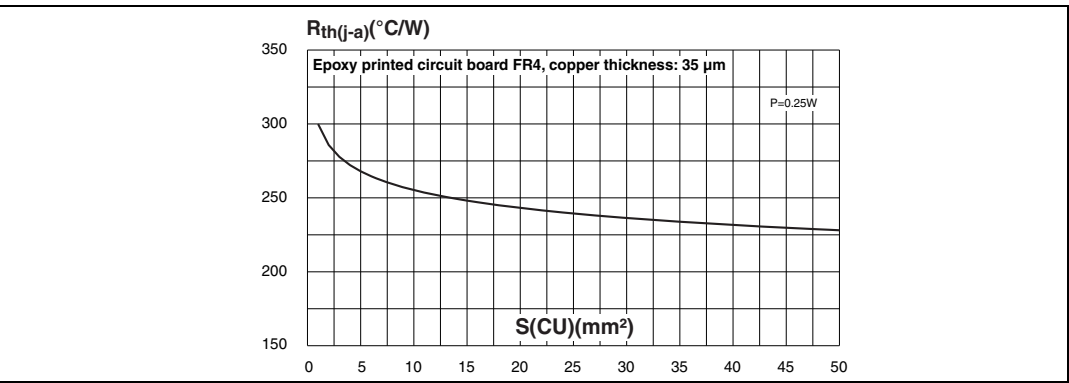


Figure 7. Thermal resistance junction to ambient versus copper surface under each lead



2 Package information

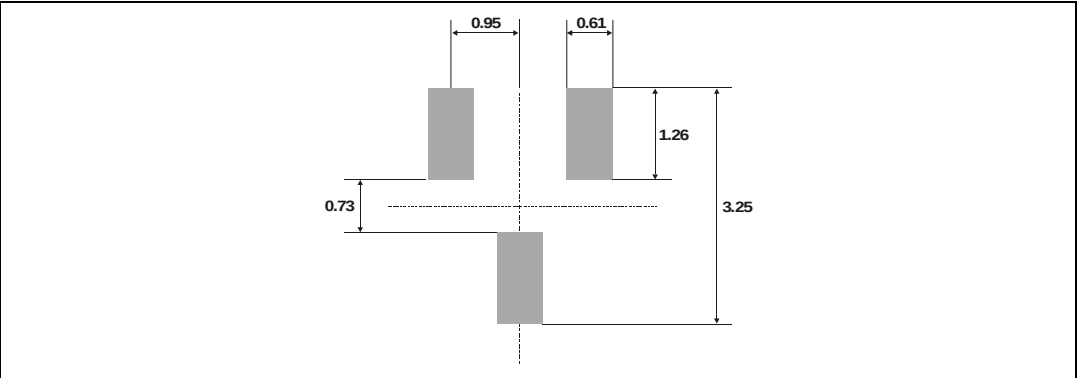
- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 6. SOT23-3L dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.89	1.4	0.035	0.055
A1	0	0.1	0	0.004
B	0.3	0.51	0.012	0.02
c	0.085	0.18	0.003	0.007
D	2.75	3.04	0.108	0.12
e	0.85	1.05	0.033	0.041
e1	1.7	2.1	0.067	0.083
E	1.2	1.6	0.047	0.063
H	2.1	2.75	0.083	0.108
L	0.6 typ.		0.024 typ.	
S	0.35	0.65	0.014	0.026

Figure 8. Footprint (dimensions in mm)



3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base Qty	Delivery mode
BAR42FILM	D94	SOT23-3L	0.01 g	3000	Tape and reel
BAR43FILM	D95				
BAR43AFILM	DB1				
BAR43CFILM	DB2				
BAR43SFILM	DA5				

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
Aug-2001	2B	Last release.
16-Apr-2005	3	Layout update. No content change.
23-Apr-2014	4	Updated ECOPACK statement.
18-Jul-2017	5	Updated figure in cover page.

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2017 STMicroelectronics – All rights reserved

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9